MBRP20200CT

Rev.F Mar.-2016

/ Descriptions

TO-3P

Schottky Barrier Diode in a TO-3P Plastic Package.

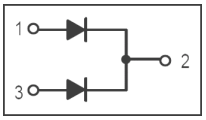
/ Features

Low power loss, high efficiency.

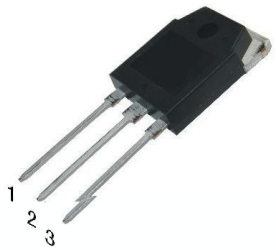
/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

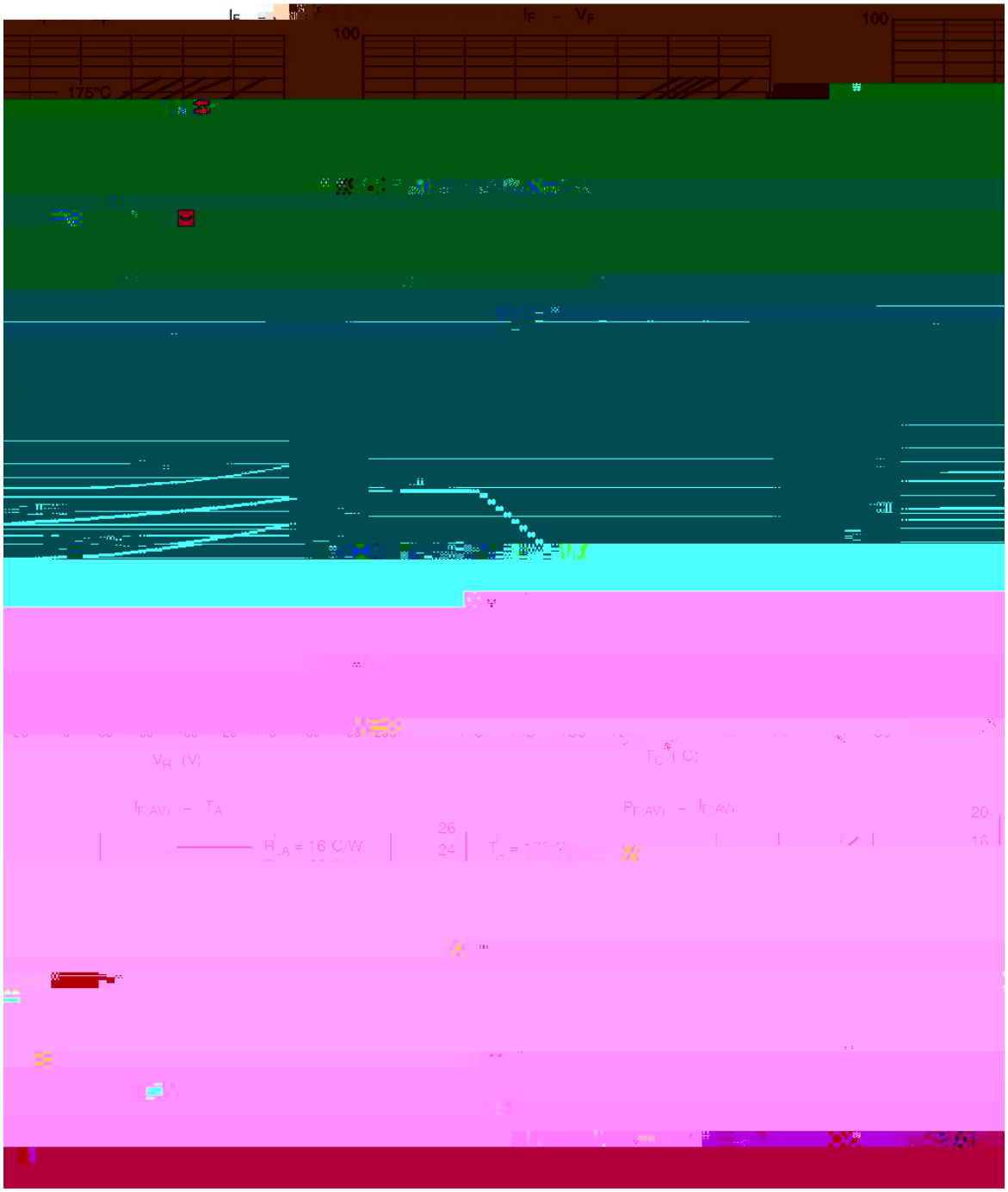
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Working Peak Reverse Voltage	V_{RWM}	200	V
Peak Repetitive Forward Current	I_{FRM}	20	A
Average Rectified Forward Current	$I_{F(AV)}$	10	A
	$I_{F(AV)}$（total）	20	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Peak Repetitive Reverse Surge Current	I_{RRM}	1.0	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	1.25	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-65～150	

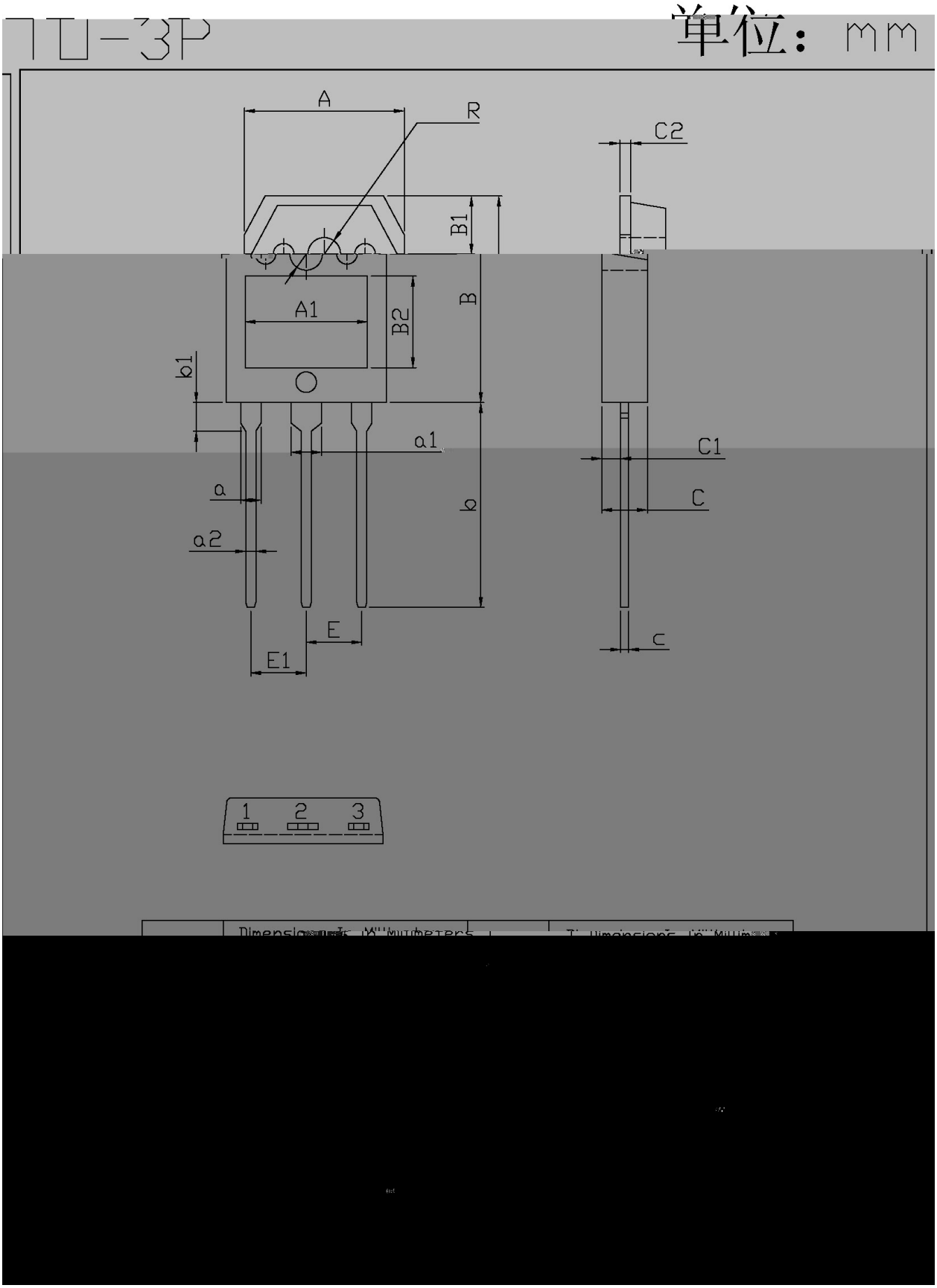
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F =10A(T_j=25)		0.8	0.9	V
		I_F =10A(T_j=125)		0.66	0.8	V
		I_F =20A(T_j=25)		0.89	1.0	V
		I_F =20A(T_j=125)		0.76	0.9	V
Instantaneous Reverse Current	I_R	V_R=200V(T_j=25)			1.0	mA
		V_R=200V(T_j=125)		0.4	50	mA
Voltage Rate of Change	dv/dt				10000	V/μs

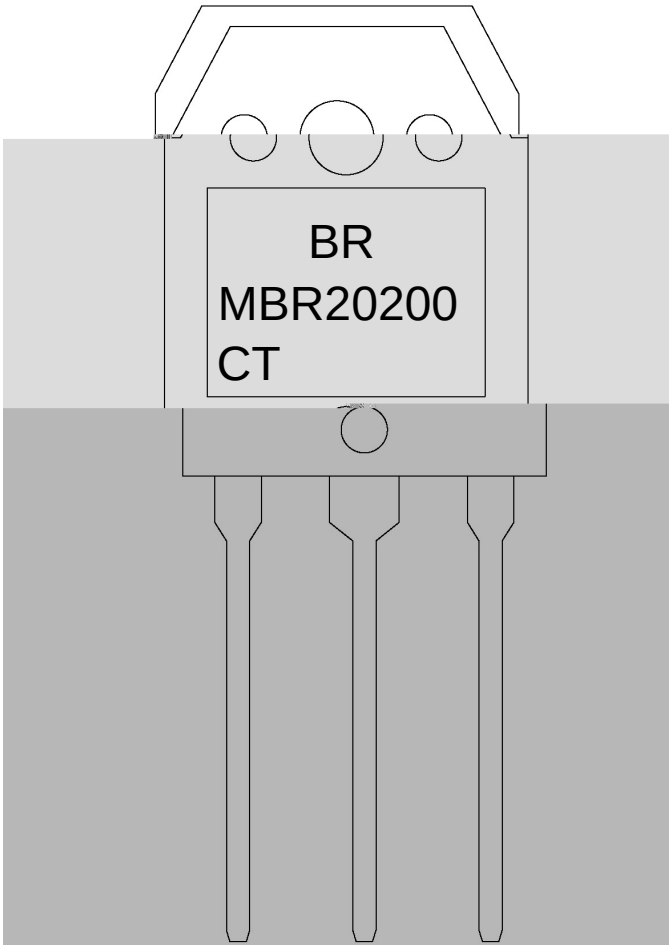
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

MBR20200

CT:

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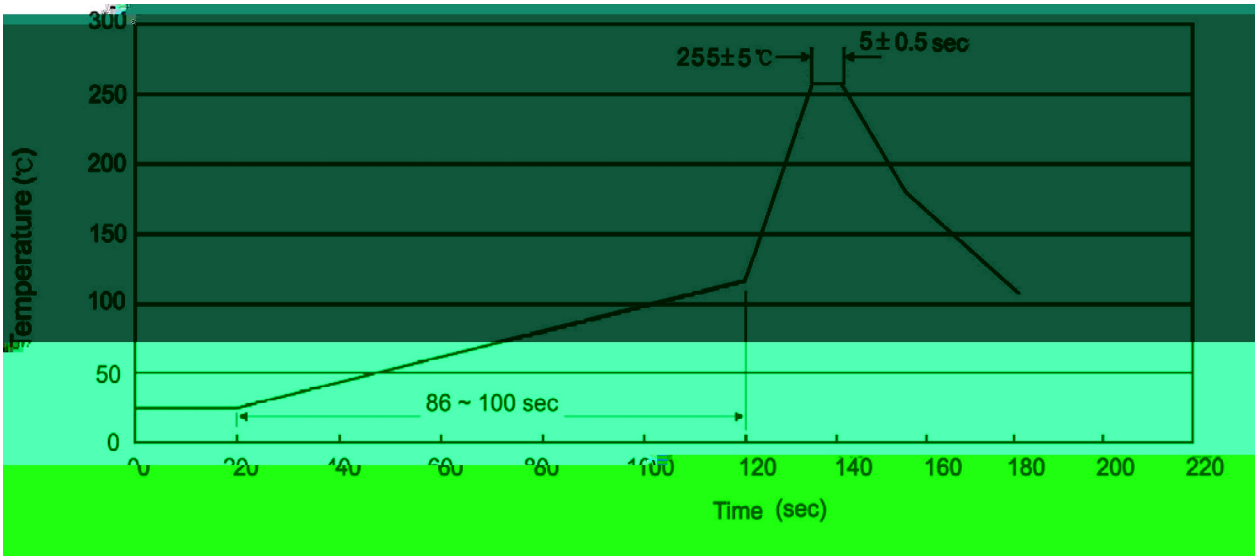
Note:

BR:	Company Code
MBR20200	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



				Note:
1	25	150	60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2	255±5		5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension		(unit mm^3)
								× ×

/ Notices